

IN THE CLAIMS

Claim 1 (**currently amended**). A process for preparing a pressure-sensitive polyacrylate adhesive, wherein

a polyacrylate composition including the atomic sequence C – S – C is admixed with at least one metal compound of formula $(L)_yM$ where

M = metal atom or metal ion

L = counterion or ligand selected from the group consisting of

halides, alkoxides, borides, hydroxides, nitrates, phosphates, perchlorates, phthalocyanines, oxinates, acetates, acetylacetonates, carbonates, formates, cyanides, naphthalocyanines, rhodanides, thiocyanates, carboxylates, chelates, resins, carbides, phosphines, alkyls, alkenyls, alkynyls, diones, aryls, substituted aryls, citrates, heterocycles, pentadienyl, amines, polyfunctional amines, ethers, and crown ethers

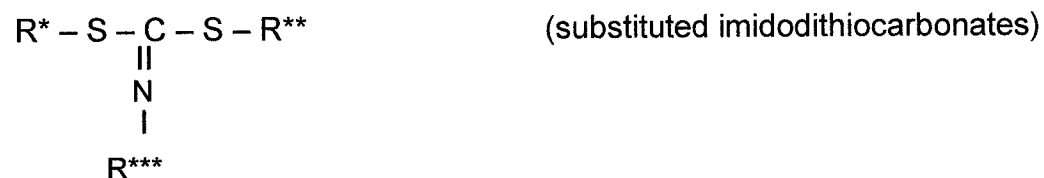
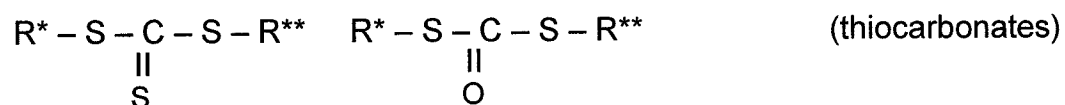
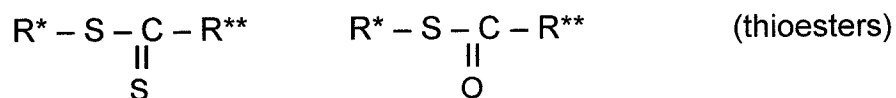
y = 0 to 6.

Claim 2 (previously presented). The process of claim 1, comprising at least the following steps:

- polymerizing a monomer mixture using at least one compound including the atomic sequence C – S – C as regulator, to form a polyacrylate composition which includes the atomic sequence C-S-C,
- additizing with metal compounds of formula $(L)_yM$,

- concentrating the resulting polyacrylate composition to form a hotmelt composition,
- crosslinking the hotmelt composition by means of actinic radiation.

Claim 3 (previously presented). The process of claim 1 or 2, wherein the compound comprising the atomic sequence C – S – C is a compound represented by one of the following structures:



where R*, R** and R*** independently of one another are aromatic or aliphatic saturated or unsaturated hydrocarbon radicals.

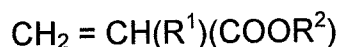
Claim 4 (previously presented). The process of claim 3, wherein
the radicals R*, R** and/or R*** are present wholly or partly in oligomeric
and/or polymeric form.

Claim 5 (previously presented). The process of claim 1 or 2, wherein
the metal compound (L)_yM is a metal salt, a metal hydroxide or a metal
complex compound.

Claim 6 (previously presented). The process of claim 2, wherein
the hotmelt composition is applied to a backing material prior to crosslinking.

Claim 7 (previously presented). The process of claim 1 or 2, wherein
the polyacrylate composition is based at least 50% by weight on acrylic
monomers.

Claim 8 (previously presented). The process of claim 1 or 2, wherein
the polyacrylate composition is based at least partly on monomers of the
formula



where

$R^1 = H \text{ or } CH_3$

$R^2 = H \text{ or a hydrocarbon radical containing 1 to 30 carbon atoms.}$

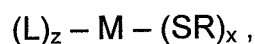
Claim 9 (previously presented). The process of claim 1 or 2, wherein

the metal M is selected from the group consisting of

copper, nickel, iron, zinc, tin, cadmium, aluminum, cobalt, silver and gold.

Claim 10 (cancelled).

Claim 11 (previously presented). A polyacrylate-based pressure-sensitive adhesive, comprising at least one metal-sulfur compound of the structure



where

M represents a metal selected from the group consisting of Cu, Ni, Fe, Zn, Cd, Al, Co, Ag and Au,

R independently at each occurrence denotes aliphatic, aromatic, saturated, unsaturated, oligomeric or polymeric radicals,

L independently at each occurrence represents ions or ligands selected from the group consisting of halides, alkoxides, borides, hydroxides, nitrates,

phosphates, perchlorates, phthalocyanines, oxinates, acetates, acetylacetonates, carbonates, formates, cyanides, naphthalocyanines, thiocyanates, carboxylates, chelates, resins, carbides, phosphines, alkyls, alkenyls, alkynyls, diones, aryls, substituted aryls, citrates, heterocycles, pentadienyl, amines, polyfunctional amines, ethers and crown ethers.

Claim 12 (previously presented). The pressure-sensitive adhesive of claim 11, comprising at least 25 ppm, based on the parent polymer, of metal-sulfur compounds of the formula $(L)_z - M - (SR)_x$.